PRECAUTIONS FOR USE

ISAHAYA small-signal transistor and diodes are designed and produced under extremely strict quality control so that they will live up to customer's expectations. However, if devices are exposed to excessive thermal, mechanical and electrical stresses, they may markedly deteriorate the characteristics and quality.

To get the best from the devices and assure the required reliability, we would like you to follow the instructions given below.

Caution for Lead Bending

When you have to bend leads so as to mount the device according to a given configuration, follow the instructions given below:

＜TO-92S Package＞

(1) Prepare a jig to prevent stresses to electrode lead or two pair of needle-nose pliers. Pinch a lead between the bending point and the body with one pair of pliers. Next, with the other pair of pliers, pinch the remaining part of lead and bend it.

(2) To make a lead bending sideways as shown in Fig.1, bend at a point on the thin portion or at a point more than 4mm down from the body. The bending angle should be less than 30° .

(3) To make a lead bending perpendicularly to the front side of the body as shown in Fig.2, bend at a point more than 4mm down from the body.

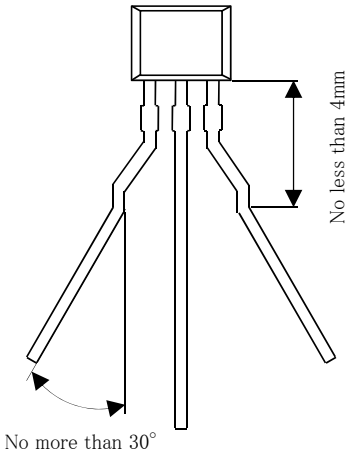

Fig.1 Bending of Leads toward Either Side.

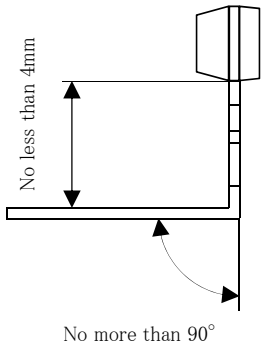

Fig.2 Lead Bending to Be Perpendicular to the Transistor Name Plate Face.

PRECAUTIONS FOR USE

＜TO-220F Package＞

(1) Prepare a jig to prevent stresses to electrode lead or two pair of needle-nose pliers. Pinch a lead between the bending point and the body with one pair of pliers. Next, with the other pair of pliers, pinch the remaining part of lead and bend it.

(2) To make a lead bending sideways as shown in Fig.1, bend at a point on the thin portion or at a point more than 4mm down from the body. The bending angle should be less than 30° .

(3) To make a lead bending perpendicularly to the front side of the body as shown in Fig.2, bend at a point more than 4mm down from the body.

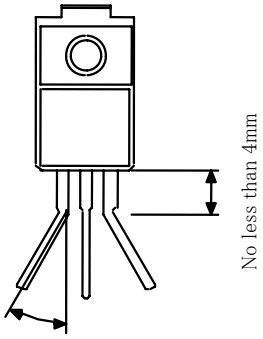

Fig.1 Bending of Leads toward Either Side.

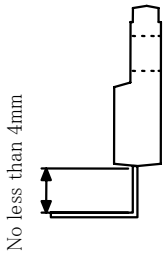

Fig.2 Lead Bending to Be Perpendicular to the Transistor Name Plate Face.